

Sub C1
1. (Amended) A tape carrier package semiconductor device, which has a tape carrier and semiconductor elements that have been packaged on the tape carrier, said tape carrier package semiconductor device comprising:

B'
an insulating tape,
a metal wiring pattern installed on one surface of the insulating tape,
a through hole that is provided in a manner so as to penetrate the insulating tape so that the insulating tape is allowed to bend,

only a first insulating protective film for insulating and covering the metal wiring pattern and the through hole on the metal-wiring-pattern side, at locations over and proximate the through hole,

a second insulating protective film for insulating and covering the through hole on the side opposite to the metal-wiring-pattern side, and

resin sealing peripheral portions where the metal wiring pattern and a semiconductor element are connected;

wherein the first and second insulating protective films are made of solder resist whose young's modulus is in the range of 5 kgf/mm² to 70 kgf/mm², and wherein no insulating protective film other than said first insulating protective film covers the metal wiring pattern on the metal wiring pattern side proximate the through hole.

B2 Sub C3
10. (Amended) A liquid crystal panel display, which is provided with a liquid crystal panel and a tape carrier package semiconductor device having a tape carrier and

semiconductor elements that have been packaged on the tape carrier so as to drive the liquid crystal panel, wherein said tape carrier comprises:

b2

- an insulating tape,
- a metal wiring pattern installed on one surface of the insulating tape,
- a through hole that is provided in a manner so as to penetrate the insulating tape so that the insulating tape is allowed to bend,
- only a first insulating protective film for insulating and covering the metal wiring pattern and the through hole on the metal-wiring-pattern side at locations over and proximate the through hole,
- a second insulating protective film for insulating and covering the through hole on the side opposite to the metal-wiring-pattern side, and
- resin for sealing periphery portions at which the semiconductor device and the metal wiring pattern are connected,

wherein the first and second insulating protective films are made of solder resist whose young's modulus is in the range of 5 kgf/mm² to 70 kgf/mm², and only the first insulating protective film insulates and covers the metal wiring pattern proximate the through hole on the metal wiring pattern side.

Amended 23. (Amended) A tape carrier package semiconductor device comprising:

b3

- an insulating tape,
- a metal wiring pattern on one surface of the insulating tape,

B3 a through hole provided in a manner so as to penetrate the insulating tape so that the insulating tape is allowed to bend,

only a first insulating solder resist protective film for insulating and covering the metal wiring pattern and the through hole on the metal-wiring-pattern side, and

a second insulating solder resist protective film for insulating and covering the through hole on the side opposite to the metal-wiring-pattern side,

wherein the first and second insulating solder resist protective films are made of solder resist whose young's modulus is in the range of 5 kgf/mm² to 70 kgf/mm², and no insulating solder resist other than said first insulating solder resist protective film covers the metal wiring pattern near the through hole on the metal wiring pattern side.

REMARKS

This is in response to the Office Action dated May 31, 2001. Claims 1-19 and 23 are pending. Attached hereto is a marked-up version of the changes made to the claims by the current amendment. The attached page/s is/are captioned "**Version With Markings To Show Changes Made.**"

The drawings stand objected to. In this regard, proposed drawing changes to Figs. 7-15 (labeling them as "prior art") are attached hereto, with the changes shown in red ink.

The disclosure stands objected to under 35 U.S.C. Section 132, and the claims stand objected to under 35 U.S.C. Section 112, first paragraph. In this regard, the Office Action contends that the subject matter added to claim 1 in the last amendment (i.e.,